xLED

xLED-EDI-6050 Pin Fin LED Heat Sink Φ60mm for Edison

Features VS Benefits

* The xLED-EDI-6050 Edison Pin Fin LED Heat Sinks are specifically designed for luminaires using the Edison LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 900 to 2,200 lumen.
* Thermal resistance range Rth 3.85°C/W.
* Modular design with mounting holes foreseen for direct mounting of Edison COB series.
* Diameter 60.0mm - standard height 50.0mm Other heights on request.
* Forged from highly conductive aluminum.

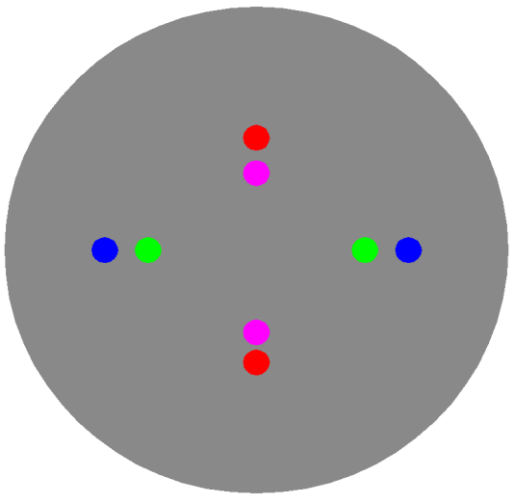
Zhaga LED engine and radiator assembly is a unified future international standardization

* Below you find an overview of Edison COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

EDISON

BJB

A.A.G. STUCCHI ideas are made of light



Edison LED Modules directly Mounting Options

Edison Opto_EdiPower® V, III HC, III HE/ CRI70/ CRI90, III SL Series :

2PHE06xxxxP32202;
2PHE09xxxxP35202;
2PHC09xxxxP32001;
2PHE13xxxxP32001;
2PSL09xxxxP12010;

With the Zhaga Book 11 holders for the green indicator marks.
BJB holder: 47.319.6294.50;
AAG.STUCCHI: 8100-G2
Without the holders for the pink indicator marks.
Direct mounting with machine screws M3x6.5mm.

Edison LED Modules directly Mounting Options

Edison Opto_EdiPower® V, III HC, III HE/ CRI70/ CRI90, III SL Series :

2PHE15xxxxP34202;
2PHE18xxxxP34202;
2PHE24xxxxP34202;
2PHE30xxxxP34202;
2PHC20xxxxP34001;
2PHC30xxxxP34001;
2PHE20xxxxP34001;
2PHE30xxxxP34001;
2PSL30xxxxP13010;

With the Zhaga Book 3 holders for the blue indicator marks.
BJB holder: 47.319.2021.50;
AAG.STUCCHI: 8101-G2
Without the holders for the red indicator marks.
Direct mounting with machine screws M3x6.5mm.

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Mingfa TECH

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Mounting Options and Drawings & Dimensions

Example:xLED-EDI-6050-B-1,2

Example:xLED-EDI-60 1 - 2 - 3

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

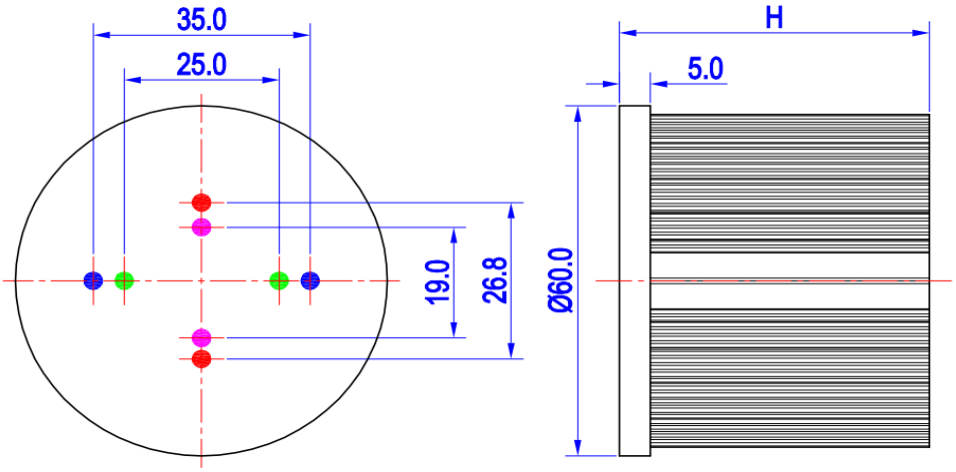
Ex.order code - 12

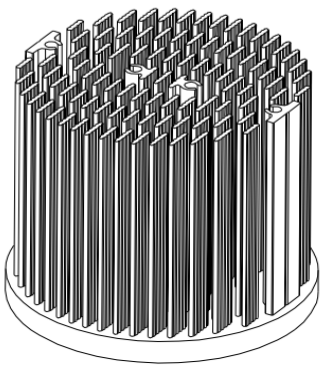
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	9~13W COB	/	M3	6.5mm	19.0mm/ 2-@180°
2		BJB Holder 47.319.2021.50	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		AAG.STUCCHI 8101-G2			
3	15~30W COB	/	M3	6.5mm	26.8mm/ 2-@180°
4		BJB Holder 47.319.2021.50	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8101-G2			





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The product deta table

Model No.	**xLED-EDI-6050**
Heatsink Size	**Φ60xH50mm**
Heatsink Material	**AL1070**
Finish	**Black Anodized**
Weight (g)	**112.0**
Dissipated power (Ths-amb,50℃)	**13.0 (W)**
Cooling surface area (mm^2)	**68473**
Thermal Resistance (Rhs-amb)	**3.85 (°C/W)**

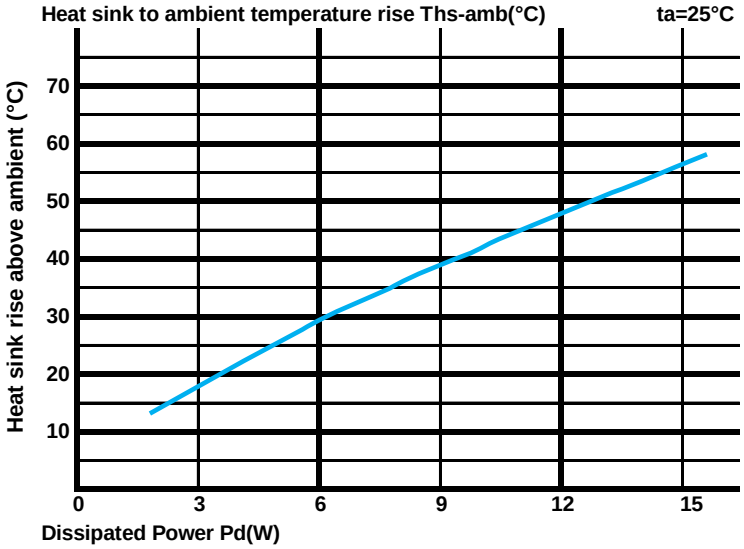
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

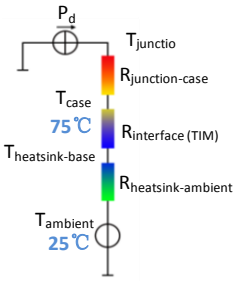
Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-EDI-6050	
Dissipated Power Pd(W)	3.0	5.67	17.0
	6.0	4.83	29.0
	9.0	4.22	38.0
	12.0	4.00	48.0
	15.0	3.73	56.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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